

ABSTRACT OF THE DISCLOSURE

An electrostatic chucking device having a laminated structure formed by sequentially laminating a first insulation layer, an electrode layer, and a second insulation layer on a metal substrate. The first and second insulation layers are formed from polyimide films. At least one adhesion layer is provided between the metal substrate and the first insulation layer, and is a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm .